Virtex-II Pro™ Platform FPGAs: Introduction and Overview

DS083-1 (v1.0) January 31, 2002

Advance Product Specification

Summary of Virtex-II Pro Features

- High-performance Platform FPGA solution including
  - Up to sixteen Rocket I/O™ embedded multi-gigabit transceiver blocks (based on Mindspeed's SkyRail™ technology)
  - Up to four IBM® PowerPC® RISC processor blocks
- Based on Virtex™-II Platform FPGA technology
  - Flexible logic resources
  - SRAM-based in-system configuration
  - Active Interconnect™ technology
  - SelectRAM™ memory hierarchy
  - Dedicated 18-bit x 18-bit multiplier blocks
  - High-performance clock management circuitry
  - SelectI/O™-Ultra technology
  - Digitally Controlled Impedance (DCI) I/O

The members and resources of the Virtex-II Pro family are shown in Table 1.

Rocket I/O Features

- Full-duplex serial transceiver (SERDES) capable of baud rates from 622 Mb/s to 3.125 Gb/s
- 80 Gb/s duplex data rate (16 channels)
- Monolithic clock synthesis and clock recovery (CDR)
- Fibre Channel, Gigabit Ethernet, 10 Gb Attachment Unit Interface (XAUI), and Infiniband-compliant transceivers
- 8-, 16-, or 32-bit selectable internal FPGA interface
- 8B /10B encoder and decoder
- 50Ω /75Ω on-chip selectable transmit and receive terminations
- Programmable comma detection
- Channel bonding support (two to sixteen channels)
- Rate matching via insertion/deletion characters
- Four levels of selectable pre-emphasis
- Five levels of output differential voltage
- Per-channel internal loopback modes
- 2.5V transceiver supply voltage

PowerPC RISC Core Features

- Embedded 300+ MHz Harvard architecture core
- Low power consumption: 0.9 mW/MHz
- Five-stage data path pipeline
- Hardware multiply/divide unit
- Thirty-two 32-bit general purpose registers
- 16 KB two-way set-associative instruction cache
- 16 KB two-way set-associative data cache
- Memory Management Unit (MMU)
  - 64-entry unified Translation Look-aside Buffers (TLB)
  - Variable page sizes (1 KB to 16 MB)
- Dedicated on-chip memory (OCM) interface
- Supports IBM CoreConnect™ bus architecture
- Debug and trace support
- Timer facilities

Table 1: **Virtex-II Pro FPGA Family Members**

Device	Rocket I/O Transceiver Blocks	PowerPC Processor Blocks	CLB (1 CLB = 4 slices = Max 128 bits)			18 X 18 Bit Multiplier Blocks	Block SelectRAM		DCMs	Max I/O Pads
			Array Row x Col	Slices	Maximum Distributed RAM (Kb)		18 Kb Blocks	Max Block RAM (Kb)		
XC2VP2	4	0	16 x 22	1,408	44	12	12	216	4	204
XC2VP4	4	1	40 x 22	3,008	94	28	28	504	4	348
XC2VP7	8	1	40 x 34	4,928	154	44	44	792	4	396
XC2VP20	8	2	56 x 46	9,280	290	88	88	1,584	8	564
XC2VP50	16	4	88 x 70	22,592	706	216	216	3,888	8	852

Virtex-II Pro Platform FPGA Technology

- SelectRAM memory hierarchy
  - Up to 4 Mb of True Dual-Port RAM in 18 Kb block SelectRAM resources
  - Up to 706 Kb of distributed SelectRAM resources
  - High-performance interfaces to external memory
- Arithmetic functions
  - Dedicated 18-bit x 18-bit multiplier blocks
  - Fast look-ahead carry logic chains
- Flexible logic resources
  - Up to 45,184 internal registers/latches with Clock Enable
  - Up to 45,184 look-up tables (LUTs) or cascadable variable (1 to 16 bits) shift registers
  - Wide multiplexers and wide-input function support
  - Horizontal cascade chain and Sum-of-Products support
  - Internal 3-state busing
- High-performance clock management circuitry
  - Up to eight Digital Clock Manager (DCM) modules
    - Precise clock de-skew
    - Flexible frequency synthesis
    - High-resolution phase shifting
  - 16 global clock multiplexer buffers in all parts
- Active Interconnect technology
  - Fourth-generation segmented routing structure
  - Fast, predictable routing delay, independent of fanout
  - Deep sub-micron noise immunity benefits
- SelectI/O-Ultra technology
  - Up to 852 user I/Os
  - Twenty two single-ended standards and five differential standards
  - Programmable LVTTL and LVCMOS sink/source current (2 mA to 24 mA) per I/O
  - Digitally Controlled Impedance (DCI) I/O: on-chip termination resistors for single-ended I/O standards
  - PCI support(1)
  - Differential signaling
    - 840 Mb/s Low-Voltage Differential Signaling I/O (LVDS) with current mode drivers
    - Bus LVDS I/O
    - HyperTransport (LDT) I/O with current driver buffers
    - Built-in DDR input and output registers
  - Proprietary high-performance SelectLink technology for communications between Xilinx devices
    - High-bandwidth data path
    - Double Data Rate (DDR) link
    - Web-based HDL generation methodology
- SRAM-based in-system configuration
  - Fast SelectMAP™ configuration
  - Triple Data Encryption Standard (DES) security option (bitstream encryption)
  - IEEE1532 support
  - Partial reconfiguration
  - Unlimited reprogrammability
  - Readback capability
- Supported by Xilinx Foundation™ and Alliance™ series development systems
  - Integrated VHDL and Verilog design flows
  - ChipScope™ Integrated Logic Analyzer
- 0.13-µm, nine-layer copper process with 90 nm high-speed transistors
- 1.5V (V_{CCINT}) core power supply, dedicated 2.5V V_{CCAUX} auxiliary and V_{CCO} I/O power supplies
- IEEE 1149.1 compatible boundary-scan logic support
- Flip-Chip and Wire-Bond Ball Grid Array (BGA) packages in standard 1.00 mm pitch
- Each device 100% factory tested

General Description

The Virtex-II Pro family is a platform FPGA for designs that are based on IP cores and customized modules. The family incorporates multi-gigabit transceivers and PowerPC CPU cores in Virtex-II Pro Series FPGA architecture. It empowers complete solutions for telecommunication, wireless, networking, video, and DSP applications.

The leading-edge 0.13µm CMOS nine-layer copper process and the Virtex-II Pro architecture are optimized for high performance designs in a wide range of densities. Combining a wide variety of flexible features and IP cores, the Virtex-II Pro family enhances programmable logic design capabilities and is a powerful alternative to mask-programmed gate arrays.

1. PCI supported in some banks only.

Architecture

Virtex-II Pro Array Overview

Virtex-II Pro devices are user-programmable gate arrays with various configurable elements and embedded cores optimized for high-density and high-performance system designs. Virtex-II Pro devices implement the following functionality:

- Embedded high-speed serial transceivers enable data bit rate up to 3.125 Gb/s per channel.
- Embedded IBM PowerPC 405 RISC CPU cores provide performance of 300+ MHz.
- SelectI/O-Ultra blocks provide the interface between package pins and the internal configurable logic. Most popular and leading-edge I/O standards are supported by the programmable IOBs.
- Configurable Logic Blocks (CLBs) provide functional elements for combinatorial and synchronous logic, including basic storage elements. BUFTs (3-state buffers) associated with each CLB element drive dedicated segmentable horizontal routing resources.
- Block SelectRAM memory modules provide large 18 Kb storage elements of True Dual-Port RAM.
- Embedded multiplier blocks are 18-bit x 18-bit dedicated multipliers.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for clock distribution delay compensation, clock multiplication and division, and coarse- and fine-grained clock phase shifting.

A new generation of programmable routing resources called Active Interconnect Technology interconnects all of these elements. The general routing matrix (GRM) is an array of routing switches. Each programmable element is tied to a switch matrix, allowing multiple connections to the general routing matrix. The overall programmable interconnection is hierarchical and designed to support high-speed designs.

All programmable elements, including the routing resources, are controlled by values stored in static memory cells. These values are loaded in the memory cells during configuration and can be reloaded to change the functions of the programmable elements.

Virtex-II Pro Features

This section briefly describes Virtex-II Pro features.

Rocket I/O Multi-Gigabit Transceiver Cores

The Rocket I/O Multi-Gigabit Transceiver core, based on Mindspeed's SkyRail technology, is a flexible parallel-to-serial and serial-to-parallel transceiver embedded core used for high-bandwidth interconnection between buses, backplanes, or other subsystems.

Multiple user instantiations in an FPGA are possible, providing up to 80 Gb/s of full-duplex raw data transfer. Each channel can be operated at a maximum data transfer rate of 3.125 Gb/s.

Each Rocket I/O core implements the following functionality:

- Serializer and deserializer (SERDES)
- Monolithic clock synthesis and clock recovery (CDR)
- Fibre Channel, Gigabit Ethernet, XAUI, and Infiniband compliant transceivers
- 8-, 16-, or 32-bit selectable FPGA interface
- 8B/10B encoder and decoder with bypassing option on each channel
- Channel bonding support (two to sixteen channels)
  - Elastic buffers for inter-chip deskewing and channel-to-channel alignment
- Receiver clock recovery tolerance of up to 75 non-transitioning bits
- 50Ω /75Ω on-chip selectable TX and RX terminations
- Programmable comma detection
- Rate matching via insertion/deletion characters
- Automatic lock-to-reference function
- Optional TX and RX data inversion
- Four levels of pre-emphasis support
- Per-channel serial and parallel transmitter-to-receiver internal loopback modes
- Cyclic Redundancy Check (CRC) support

PowerPC 405 Processor Block

The PPC405 RISC CPU can execute instructions at a sustained rate of one instruction per cycle. On-chip instruction and data cache reduce design complexity and improve system throughput.

The PPC405 features include:

- PowerPC RISC CPU
  - Implements the PowerPC User Instruction Set Architecture (UISA) and extensions for embedded applications
  - Thirty-two 32-bit general purpose registers (GPRs)
  - Static branch prediction
  - Five-stage pipeline with single-cycle execution of most instructions, including loads/stores
  - Unaligned and aligned load/store support to cache, main memory, and on-chip memory
  - Hardware multiply/divide for faster integer arithmetic (4-cycle multiply, 35-cycle divide)
  - Enhanced string and multiple-word handling
  - Big/little endian operation support
- Storage Control
  - Separate instruction and data cache units, both two-way set-associative and non-blocking
  - Eight words (32 bytes) per cache line
  - 16 KB array Instruction Cache Unit (ICU), 16 KB array Data Cache Unit (DCU)

  - Operand forwarding during instruction cache line fill
  - Copy-back or write-through DCU strategy
  - Doubleword instruction fetch from cache improves branch latency
- Virtual mode memory management unit (MMU)
  - Translation of the 4 GB logical address space into physical addresses
  - Software control of page replacement strategy
  - Supports multiple simultaneous page sizes ranging from 1 KB to 16 MB
- OCM controllers provide dedicated interfaces between Block SelectRAM memory and processor core instruction and data paths for high-speed access
- PowerPC timer facilities
  - 64-bit time base
  - Programmable interval timer (PIT)
  - Fixed interval timer (FIT)
  - Watchdog timer (WDT)
- Debug Support
  - Internal debug mode
  - External debug mode
  - Debug Wait mode
  - Real Time Trace debug mode
  - Enhanced debug support with logical operators
  - Instruction trace and trace-back support
  - Forward or backward trace
- Two hardware interrupt levels support
- Advanced power management support

Input/Output Blocks (IOBs)

IOBs are programmable and can be categorized as follows:

- Input block with an optional single data rate (SDR) or double data rate (DDR) register
- Output block with an optional SDR or DDR register and an optional 3-state buffer to be driven directly or through an SDR or DDR register
- Bidirectional block (any combination of input and output configurations)

These registers are either edge-triggered D-type flip-flops or level-sensitive latches.

IOBs support the following single-ended I/O standards:

- LVTTL
- LVCMOS (3.3V, 2.5V, 1.8V, and 1.5V)
- PCI (33 and 66 MHz)
- GTL and GTLP
- HSTL 1.5V and 1.8V (Class I, II, III, and IV)
- SSTL (3.3V and 2.5V, Class I and II)

The DCI I/O feature automatically provides on-chip termination for each single-ended I/O standard.

The IOB elements also support the following differential signaling I/O standards:

- LVDS and Extended LVDS (2.5V only)
- BLVDS (Bus LVDS)
- ULVDS
- LDT

Two adjacent pads are used for each differential pair. Two or four IOB blocks connect to one switch matrix to access the routing resources.

Configurable Logic Blocks (CLBs)

CLB resources include four slices and two 3-state buffers. Each slice is equivalent and contains:

- Two function generators (F & G)
- Two storage elements
- Arithmetic logic gates
- Large multiplexers
- Wide function capability
- Fast carry look-ahead chain
- Horizontal cascade chain (OR gate)

The function generators F & G are configurable as 4-input look-up tables (LUTs), as 16-bit shift registers, or as 16-bit distributed SelectRAM memory.

In addition, the two storage elements are either edge-triggered D-type flip-flops or level-sensitive latches.

Each CLB has internal fast interconnect and connects to a switch matrix to access general routing resources.

Block SelectRAM Memory

The block SelectRAM memory resources are 18 Kb of True Dual-Port RAM, programmable from 16K x 1 bit to 512 x 36 bit, in various depth and width configurations. Each port is totally synchronous and independent, offering three "read-during-write" modes. Block SelectRAM memory is cascadable to implement large embedded storage blocks. Supported memory configurations for dual-port and single-port modes are shown in Table 2.

Table 2: **Dual-Port and Single-Port Configurations**

16K x 1 bit	4K x 4 bits	1K x 18 bits
8K x 2 bits	2K x 9 bits	512 x 36 bits

18 X 18 Bit Multipliers

A multiplier block is associated with each SelectRAM memory block. The multiplier block is a dedicated 18 x 18-bit 2s complement signed multiplier, and is optimized for operations based on the block SelectRAM content on one port. The 18 x 18 multiplier can be used independently of the block SelectRAM resource. Read/multiply/accumulate operations and DSP filter structures are extremely efficient.

Both the SelectRAM memory and the multiplier resource are connected to four switch matrices to access the general routing resources.

Global Clocking

The DCM and global clock multiplexer buffers provide a complete solution for designing high-speed clock schemes.

Up to eight DCM blocks are available. To generate deskewed internal or external clocks, each DCM can be used to eliminate clock distribution delay. The DCM also provides 90-, 180-, and 270-degree phase-shifted versions of its output clocks. Fine-grained phase shifting offers high-resolution phase adjustments in increments of $^{1}/_{256}$ of the clock period. Very flexible frequency synthesis provides a clock output frequency equal to a fractional or integer multiple of the input clock frequency. For exact timing parameters, see **Virtex-II Pro™ Platform FPGAs: DC and Switching Characteristics (Module 3)**.

Virtex-II Pro devices have 16 global clock MUX buffers, with up to eight clock nets per quadrant. Each clock MUX buffer can select one of the two clock inputs and switch glitch-free from one clock to the other. Each DCM can send up to four of its clock outputs to global clock buffers on the same edge. Any global clock pin can drive any DCM on the same edge.

Routing Resources

The IOB, CLB, block SelectRAM, multiplier, and DCM elements all use the same interconnect scheme and the same access to the global routing matrix. Timing models are shared, greatly improving the predictability of the performance of high-speed designs.

There are a total of 16 global clock lines, with eight available per quadrant. In addition, 24 vertical and horizontal long lines per row or column, as well as massive secondary and local routing resources, provide fast interconnect. Virtex-II Pro buffered interconnects are relatively unaffected by net fanout, and the interconnect layout is designed to minimize crosstalk.

Horizontal and vertical routing resources for each row or column include:

- 24 long lines
- 120 hex lines
- 40 double lines
- 16 direct connect lines (total in all four directions)

Boundary Scan

Boundary-scan instructions and associated data registers support a standard methodology for accessing and configuring Virtex-II Pro devices, complying with IEEE standards 1149.1 and 1532. A system mode and a test mode are implemented. In system mode, a Virtex-II Pro device will continue to function while executing non-test boundary-scan instructions. In test mode, boundary-scan test instructions control the I/O pins for testing purposes. The Virtex-II Pro Test Access Port (TAP) supports BYPASS, PRELOAD, SAMPLE, IDCODE, and USERCODE non-test instructions. The EXTEST, INTEST, and HIGHZ test instructions are also supported.

Configuration

Virtex-II Pro devices are configured by loading the bitstream into internal configuration memory using one of the following modes:

- Slave-serial mode
- Master-serial mode
- Slave SelectMAP mode
- Master SelectMAP mode
- Boundary-Scan mode (IEEE 1532)

A Data Encryption Standard (DES) decryptor is available on-chip to secure the bitstreams. One or two triple-DES key sets can be used to optionally encrypt the configuration data.

The Xilinx System Advanced Configuration Enviornment (System ACE) family offers high-capacity and flexible solution for FPGA configuration as well as program/data storage for the processor. See **DS080**, ***System ACE CompactFlash Solution*** for more information.

Readback and Integrated Logic Analyzer

Configuration data stored in Virtex-II Pro configuration memory can be read back for verification. Along with the configuration data, the contents of all flip-flops/latches, distributed SelectRAM, and block SelectRAM memory resources can be read back. This capability is useful for real-time debugging.

The Xilinx ChipScope Integrated Logic Analyzer (ILA) cores and Integrated Bus Analyzer (IBA) cores, along with the ChipScope Pro Analyzer software, provide a complete solution for accessing and verifying user designs within Virtex-II Pro devices.

IP Core and Reference Support

Intellectual Property is part of the Platform FPGA solution. In addition to the existing FPGA fabric cores, the list below shows some of the currently available hardware and software intellectual properties specially developed for Virtex-II Pro by Xilinx. Each IP core is modular, portable, Real-Time Operating System (RTOS) independent, and CoreConnect compatible for ease of design migration. Refer to **www.xilinx.com** for the latest and most complete list of cores.

Hardware Cores

- Bus Infrastructure cores (arbiters, bridges, and more)
- Memory cores (Flash, SRAM, and more)
- Peripheral cores (UART, IIC, and more)
- Networking cores (ATM, Ethernet, and more)

Software Cores

- Boot code
- Test code
- Device drivers
- Protocol stacks
- RTOS integration
- Customized board support package

Virtex-II Pro Device/Package Combinations and Maximum I/Os

Offerings include ball grid array (BGA) packages with 1.0 mm pitch. In addition to traditional wire-bond interconnects, flip-chip interconnect is used in some of the BGA offerings. The use of flip-chip interconnect offers more I/Os than are possible in wire-bond versions of the similar packages. Flip-chip construction offers the combination of high pin count and excellent power dissipation.

The Virtex-II Pro device/package combination table (Table 3) details the maximum number of I/Os for each device and package using wire-bond or flip-chip technology.

- FG denotes wire-bond fine-pitch BGA (1.00 mm pitch).
- FF denotes flip-chip fine-pitch BGA (1.00 mm pitch).
- BF denotes flip-chip fine-ptich BGA (1.27 mm pitch).

Table 3: **Virtex-II Pro Device/Package Combinations and Maximum Number of Available I/Os (Advance Information)**

Package	Pitch (mm)	Size (mm)	User Available I/Os				
			XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VP50
FG256	1.00	17 x 17	140	140			
FG456	1.00	23 x 23	156	248	248		
FF672	1.00	27 x 27	204	348	396		
FF896	1.00	31 x 31			396	556	
FF1152	1.00	35 x 35				564	692
FF1517	1.00	40 x 40					852
BF957	1.27	40 x 40				564	584

Virtex-II Pro Ordering Information

Virtex-II Pro ordering information is shown in Figure 1.

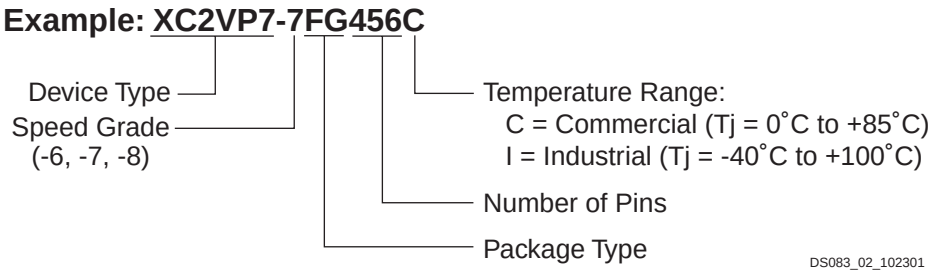

Figure 1: **Virtex-II Pro Ordering Information**

NOTE: Maximum serial transceiver baud rates for flipchip and wirebond packages are 3.125 Gb/s and 2.5 Gb/s respectively.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.

Virtex-II Pro Data Sheet Modules

The Virtex-II Pro Data Sheet contains the following modules:

- **Virtex-II Pro Platform FPGAs: Introduction and Overview (Module 1)**
- **Virtex-II Pro™ Platform FPGAs: Functional Description (Module 2)**
- **Virtex-II Pro™ Platform FPGAs: DC and Switching Characteristics (Module 3)**
- **Virtex-II Pro™ Platform FPGAs: Pinout Information (Module 4)**